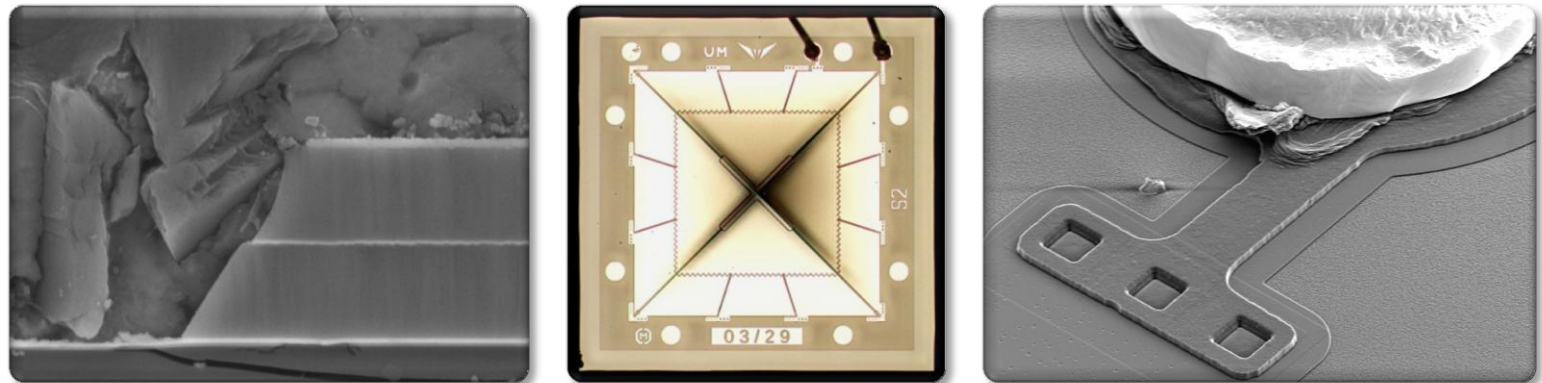


VM1000

Vesper Piezoelectric MEMS Microphone

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Product Analysis Report

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